Schottky Barrier Diode

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current and are offered in a Chip Scale Package (CSP) to reduce board space. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

Features

- Low Forward Voltage Drop 400 mV @ 500 mA
- Low Reverse Current 15 μA @ 10 V VR
- 500 mA of Continuous Forward Current
- ESD Rating Human Body Model: Class 3B
 - Machine Model: Class C
- High Switching Speed
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- · Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Reverse Voltage		V _R	30	V
Forward Current (DC)		IF	500	mA
Forward Surge Current (60 Hz @ 1 cycle)		I _{FSM}	10	А
ESD Rating:	Human Body Model Machine Model	ESD	> 8 > 400	kV V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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30 V SCHOTTKY BARRIER DIODE





DSN2 (0402) CASE 152AC

MARKING DIAGRAM

PIN 1 05F30 YYY

05F30 = Specific Device Code YYY = Year Code

ORDERING INFORMATION

Device	Package	Shipping†
NSR05F30NXT5G	DSN2 (Pb-Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Characteristic		Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			240 521	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D			94 1.3	°C/W W
Storage Temperature Range	T _{stg}			-40 to +125	°C
Junction Temperature	TJ			+150	°C

Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
 Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 10 V) (V _R = 30 V)	I _R			15 75	μΑ
Forward Voltage (I _F = 100 mA) (I _F = 500 mA)	V _F		0.320 0.400	0.360 0.430	V

TYPICAL CHARACTERISTICS

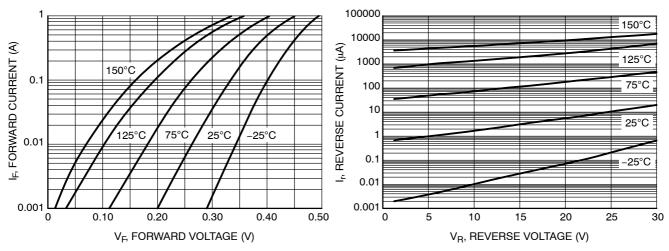


Figure 1. Forward Voltage

Figure 2. Leakage Current

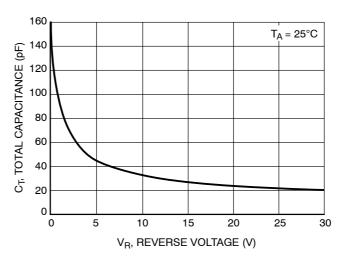
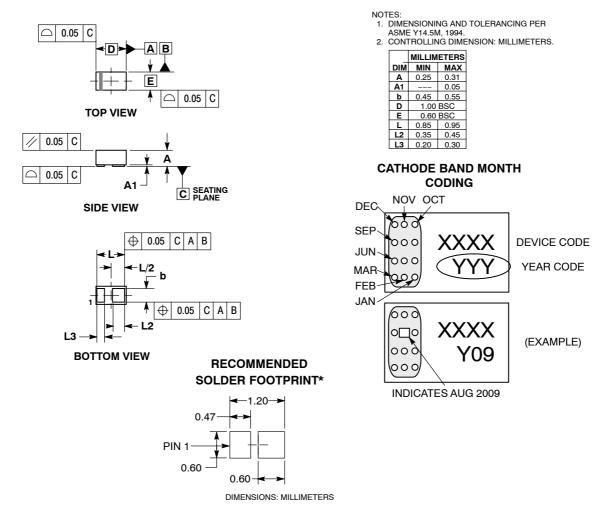


Figure 3. Total Capacitance

PACKAGE DIMENSIONS

DSN2, 1.0x0.6, 0.575P, (0402) CASE 152AC-01 ISSUE B



See Application Note AND8398/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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